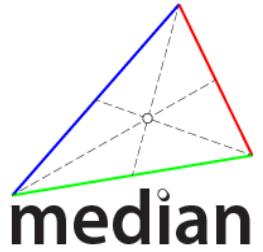


MEDIAN 2013

May 30-31, 2013

Avignon • France

co-located @ ETS 2013



2nd Workshop on Manufacturable and Dependable Multicore Architectures at Nanoscale

<http://www.median-project.eu/median2013.htm>

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Salvatore Pontarelli, Univ. Roma "Tor Vergata", Italy

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Call for Submissions to MEDIAN 2013

The MEDIAN Workshop provides an environment where ideas are exchanged and discussed, and new cooperations are created as researchers from the academic and industrial domains share their recent findings, theories and on-going work.

Workshop scope

Constant advances in manufacturing yield and field reliability are important enabling factors for electronic devices pervading our lives, from medical to consumer electronics, from railways to the automotive and space scenarios. At the same time, both technology and architectures are today at a turning point; many ideas are being proposed to postpone the end of Moore's law, such as extending CMOS technology as well as finding alternatives to it like CNTFET, QCA, memristors, etc. At the architectural level, the spin towards higher frequencies and aggressive dynamic instruction scheduling has been replaced by the trend of including many simpler cores on a single die. These paradigm shifts imply new dependability issues and require a rethinking of design, manufacturing, testing, and validation of reliable next-generation systems. These manufacturability and dependability issues will be resolved efficiently only if a cross-layer approach that takes into account technology, circuit and architectural aspects will be developed. Topics of interest include (but are not limited to):

- ◊ Methodologies/techniques for manufacturing reliable nanoscale devices
- ◊ System level design, on-line testing/fault tolerance
- ◊ Verification and Validation/Debug Methodologies
- ◊ Fault tolerance for space applications
- ◊ Fault tolerance for transportation systems
- ◊ Fault tolerance for medical devices

Paper submission

Perspective authors are invited to submit an abstract, maximum 4 pages, prepared according to the Springer format. Detailed information about the submission process will be made available on the workshop web page.

Paper publication and Presenter Registration

Accepted abstracts will be distributed during the workshop and published on the Workshop's website. Every accepted paper must have at least one author registered to the workshop by the time the camera-ready is submitted; the author is also expected to attend the workshop and present the contribution. Extended versions of the accepted abstracts are also eligible to undergo a second round of reviews for possible publication in a special session of an archival journal.

Important dates

Submission deadline: 15th March, 2013
Notification of acceptance: 15th April, 2013
Camera ready final version: 30th April, 2013

Based on the availability of COST Action IC1103 funding, authors of accepted contributions will be eligible for travel reimbursement. In case of limited budget availability, the selection of beneficiaries will be based on the following criteria, in priority order: 1) Young researchers (Master thesis / Ph.D students); 2) Balance of allocation among different Working Groups; and 3) First come first serve (date of submission of contribution).